

Environmental testing —

Part 2-58: Tests — Test Td: Test methods for solderability, resistance to dissolution of metallization and to soldering heat of surface mounting devices (SMD)

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National foreword

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The UK participation in its preparation was entrusted to Technical Committee EPL/501, Electronic assembly technology, which has the responsibility to:

- aid enquirers to understand the text;
- present to the responsible international/European committee any enquiries on the interpretation, or proposals for change, and keep the UK interests informed;
- monitor related international and European developments and promulgate them in the UK.

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From 1 January 1997, all IEC publications have the number 60000 added to the old number. For instance, IEC 27-1 has been renumbered as IEC 60027-1. For a period of time during the change over from one numbering system to the other, publications may contain identifiers from both systems.

Cross-references

Attention is drawn to the fact that CEN and CENELEC Standards normally include an annex which lists normative references to international publications with their corresponding European publications. The British Standards which implement these international or European publications may be found in the BSI Standards Catalogue under the section entitled “International Standards Correspondence Index”, or by using the “Find” facility of the BSI Standards Electronic Catalogue.

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Summary of pages

This document comprises a front cover, an inside front cover, the EN title page, pages 2 to 18, an inside back cover and a back cover.

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Environmental testing
Part 2-58: Tests - Test Td: Test methods for solderability,
resistance to dissolution of metallization and to soldering heat of
surface mounting devices (SMD)
(IEC 60068-2-58:1999)

Essais d'environnement
Partie 2-58: Essais - Essai Td: Méthodes
d'essai de la soudabilité, de la
résistance de la métallisation à la
dissolution et de la résistance à la
chaleur de soudage des composants
pour montage en surface (CSM)
(CEI 60068-2-58:1999)

Umweltprüfungen
Teil 2-58: Prüfungen - Prüfung Td:
Prüfverfahren für Lötbarkeit,
Widerstandsfähigkeit gegenüber
Auflösen der Metallisierung und
Lötwärmebeständigkeit bei
oberflächenmontierbaren
Bauelemente (SMD)
(IEC 60068-2-58:1999)

This European Standard was approved by CENELEC on 1999-04-01. CENELEC members are bound to comply with the CEN/CENELEC Internal Regulations which stipulate the conditions for giving this European Standard the status of a national standard without any alteration.

Up-to-date lists and bibliographical references concerning such national standards may be obtained on application to the Central Secretariat or to any CENELEC member.

This European Standard exists in three official versions (English, French, German). A version in any other language made by translation under the responsibility of a CENELEC member into its own language and notified to the Central Secretariat has the same status as the official versions.

CENELEC members are the national electrotechnical committees of Austria, Belgium, Czech Republic, Denmark, Finland, France, Germany, Greece, Iceland, Ireland, Italy, Luxembourg, Netherlands, Norway, Portugal, Spain, Sweden, Switzerland and United Kingdom.

CENELEC

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

Central Secretariat: rue de Stassart 35, B - 1050 Brussels

Foreword

The text of document 91/157/FDIS, future edition 2 of IEC 60068-2-58, prepared by IEC TC 50, Environmental testing, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as EN 60068-2-58 on 1999-04-01.

This European Standard supersedes HD 323.2.58 S1:1991.

The following dates were fixed:

- latest date by which the EN has to be implemented
at national level by publication of an identical
national standard or by endorsement (dop) 2000-01-01
- latest date by which the national standards conflicting
with the EN have to be withdrawn (dow) 2002-01-01

Annexes designated "normative" are part of the body of the standard.

Annexes designated "informative" are given for information only.

In this standard, annexes A and ZA are normative and annex B is informative.

Annex ZA has been added by CENELEC.

Endorsement notice

The text of the International Standard IEC 60068-2-58:1999 was approved by CENELEC as a European Standard without any modification.

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ENVIRONMENTAL TESTING –

Part 2-58: Tests – Test Td – Test methods for solderability, resistance to dissolution of metallization and to soldering heat of surface mounting devices (SMD)

1 Scope

This part of IEC 60068 outlines test Td, applicable to surface mounting devices (SMD). Soldering tests applicable to SMD in IEC 60068-2-69 and to other electrotechnical products are in IEC 60068-2-20 and IEC 60068-2-54, for which guidance is given in IEC 60068-2-44.

This standard provides standard procedures for determining the solderability, resistance to dissolution of metallization and resistance to soldering heat of surface mounting devices (SMD) (hereinafter referred to as specimens).

The procedures use either a solder bath or reflow method and are applicable only to specimens or products designed to withstand short term immersion in molten solder or limited exposure to reflow systems.

2 Normative references

The following normative documents contain provisions which, through reference in this text, constitute provisions of this part of IEC 60068. At the time of publication, the editions indicated were valid. All normative documents are subject to revision, and parties to agreements based on this part of IEC 60068 are encouraged to investigate the possibility of applying the most recent editions of the normative documents indicated below. Members of IEC and ISO maintain registers of currently valid International Standards.

IEC 60068-1:1988, *Environmental testing – Part 1: General and guidance*

IEC 60068-2-20:1979, *Environmental testing – Part 2: Tests – Test T: Soldering*

IEC 60068-2-44:1995, *Environmental testing – Part 2: Tests – Guidance on test T: Soldering*

IEC 60068-2-54:1985, *Environmental testing – Part 2: Tests – Test Ta: Soldering – Solderability testing by the wetting balance method*

IEC 60068-2-69:1995, *Environmental testing – Part 2: Tests – Test Te: Solderability testing of electronic components for surface mount technology by the wetting balance method*

IEC 60249-2-4:1987, *Base materials for printed circuits – Part 2: Specifications – Specification No. 4: Epoxide woven, glass fabric, copper-clad laminated sheet, general purpose grade*

IEC 60749:1996, *Semiconductor devices – Mechanical and climatic test methods*

3 Terms and definitions

For the purpose of this part of IEC 60068, the terms and definitions as defined in IEC 60068-1 and IEC 60068-2-20 apply.